

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2356	(29/840).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/22 15:34
L2	778	(29/841).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/22 15:34
L3	536	(29/855).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/22 15:42
L4	117	(361/743).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/22 15:42
L5	279	(361/763).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/22 15:43
L6	2838	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/22 15:43
L7	1	(1 2 3 4 5 6) and(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) with (solder near2 mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:24

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L8	2	((PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) with (solder near2 mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)).clm.	US-PGPUB	OR	ON	2006/05/22 18:24
L9	52	("5,107,328" "5,128,831" "5,138,434" "5,593,927" "5,677,566" "5,696,033" "5,704,116" "5,729,896" "5,739,585" "5,801,350" "5,815,000" "5,842,273" "5,851,845" "5,866,953" "5,891,753" "5,893,726" "5,898,224" "5,933,713" "5,938,956" "5,946,553" "5,958,100" "5,985,043" "5,986,209" "5,989,941" "5,990,566" "5,994,784").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L10	50	("6,008,070" "6,008,014" "6,018,249" "6,020,629" "6,025,728" "6,028,365" "6,046,496" "6,048,744" "6,048,755" "6,049,125" "6,066,514" "6,072,233" "6,072,236" "6,075,288" "6,081,429" "6,089,920" "6,094,058" "6,097,087" "6,103,547" "6,107,122" "6,107,680" "6,117,382" "6,124,634" "6,150,717" "6,159,764").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L11	22	("6,326,687" "6,326,697" "6,326,698" "6,329,220" "6,329,222" "6,331,221" "6,331,453" "6,332,766" "6,451,709" "6,589,820" "6,664,139").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L12	52	("6,172,419" "6,184,465" "6,189,208" "6,198,172" "6,208,519" "6,210,992" "6,215,175" "6,228,548" "6,228,687" "6,229,202" "6,246,108" "6,252,308" "6,258,623" "6,258,624" "6,259,153" "6,277,671" "6,284,571" "6,291,894" "6,294,839" "6,303,981" "6,303,985" "6,310,390" "6,314,639" "6,316,285" "6,326,242" "6,326,244").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L13	176	L9 L10 L11 L12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25

EAST Search History

L14	14	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) with (solder near2 mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L15	223	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) and (solder near2 mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L16	10	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) same (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) and (solder near2 mask solder near2 resist resist near2 pattern) same(solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L17	77	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) and (solder near2 mask solder near2 resist resist near2 pattern) and(solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L18	60	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with pad with (mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L19	695	pad with (prevent\$4 avoid) with oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L20	80	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with pad and pad with (prevent\$4 avoid) with oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25

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L21	1092	insulat\$5 with pad with solder with (ball bump c4 flip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L22	388	L21 and pad with (protect\$5 prevent avoid)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L23	371	L22 and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L24	3	("4489365" "5237131" "6011695").PN. OR ("6714421"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L25	86	("5107328" "5128831" "5138434" "5593927" "5677566" "5696033" "5704116" "5729896" "5739585" "5801350" "5815000" "5842273" "5851845" "5866953" "5891753" "5893726" "5898224" "5933713" "5938956" "5946553" "5958100" "5985043" "5986209" "5989941" "5990566" "5994784" "6008070" "6018249" "6020629" "6025728" "6028365" "6046496" "6048744" "6048755" "6049125" "6066514" "6072233" "6075288" "6081429" "6089920" "6094058" "6097087" "6103547" "6107122" "6107680" "6117382" "6124634" "6150717" "6159764" "6172419" "6184465" "6189208" "6198172" "6208519" "6210992" "6215175" "6228548" "6228687" "6229202" "6246108" "6258623" "6258624" "6259153" "6277671" "6284571" "6291894" "6294839" "6303981" "6303985" "6310390" "6314639" "6316285" "6326242" "6326244" "6326687" "6326697" "6326698" "6329220" "6329222" "6331221" "6331453" "6332766" "RE36469").PN. OR ("6622380").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L26	44	("2672681" "3235414" "3264146" "3970239" "4216035" "4601763" "4940181" "5004508" "5122200" "5177134" "5255839" "5386624" "5435481" "5442240" "5499756" "5583747").PN. OR ("5704116"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25

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L27	38	("4604644" "5084961" "5089440" "5121190" "5194930" "5274913" "5400950" "5542601" "5578525" "5615477" "5704116" "5710071").PN. OR ("5953814"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L28	144	andujar.xa.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L29	70	L28 and pad	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L30	4	("5391924" "6011694" "6054652").PN. OR ("6791199"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L31	61	("4791075" "5216278" "5474957" "5602059" "5650662" "5663530" "5679978" "5710695" "5737191").PN. OR ("6011694"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L32	2083	protect\$4 with exposed with pad	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L33	1950	protect\$4 with exposed with pad and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L34	464	protect\$4 with exposed with pad with (insulat\$3 dielectric) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L35	66	protect\$4 with exposed with pad and "174"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L36	2	"6217987".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L37	1	"6217987".pn.	USPAT	OR	ON	2006/05/22 18:25

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L38	46	("3356624" "4504607" "4510276" "4615950" "4713298" "4750976" "4752499" "4820549" "4888269" "4902726" "4948700" "4990395" "5009982" "5021472" "5055321" "5055378" "5061744" "5137936" "5175060" "5302492" "5519177" "5532094" "5741575" "5753722" "5948514").PN. OR ("6217987"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L39	16	("5321210" "5322593" "5337466" "5426849" "5590461" "5628852" "5686702" "5745984" "6049123" "6214641").PN. OR ("6418615"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L40	2	"6418615".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L41	0	US005578525A	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L42	2	"5578525".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L43	86	"5,432,734"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L44	2	"5,432,734".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L45	28	("5578525").URPN.	USPAT	OR	ON	2006/05/22 18:25

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L46	32	("20010013653" "20020012234" "4801998" "5194934" "5222014" "5231036" "5463229" "5578525" "5579207" "5786589" "5821532" "5858815" "5867368" "5907151" "5925898" "5949655" "5962810" "5973337" "5977624" "6005965" "6011310" "6028354" "6046070" "6122009" "6130448" "6143981" "6144507" "6247229" "6281568" "6291884" "6342406" "6396043"). PN. OR ("6627864").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L47	1	"5,178,685".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L48	12	("5178685").URPN.	USPAT	OR	ON	2006/05/22 18:25
L49	129	(hole opening) with (solder near2 (resist mask) with trace)	USPAT	OR	ON	2006/05/22 18:25
L50	24	("3823469" "4050621" "4604644" "4605153" "4803450" "4837609" "5060844" "5133495" "5148265" "5148266" "5160409" "5400220" "5519580" "5534127" "5547740" "5551627" "5558271" "5615477" "5801446" "5808874" "5849750" "5885849" "6130448").PN. OR ("6465747").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L51	104	trace with pad with short with circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/05/22 18:25
L52	1	"6622380".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/05/22 18:25
L53	0	solde adj mask with flux and "174". ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L54	0	solder near2 mask with flux and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L55	0	solder near2 mask and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25

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L56	8221	solder near2 mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L57	0	L56 and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L58	627	solder near2 mask same PCB	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L59	369	L58 and (IC chip integrated adj circuit wafer die semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L60	195	L58 and (IC chip integrated adj circuit wafer die semiconductor).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L61	537	solder near2 mask same BGA	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L62	377	L61 and (IC chip integrated adj circuit wafer die semiconductor).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L63	328	L62 not L60	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L64	58	pad with circuit adj board with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25

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L65	2	"6806560".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L66	15	("4786545" "5055321" "5278429" "5473512" "5519251" "5756380" "5816478" "5834832" "5872399" "5925403" "6197615" "6286207" "6288451" "6323542" "6344753").PN. OR ("6806560"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L67	377	L61 and (IC chip integrated adj circuit wafer die semiconductor).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L68	18	(US-20010013425-\$ or US-20020195272-\$ or US-20030201309-\$ or US-20010013653-\$ or US-20040046252-\$ or US-20020066948-\$).did. or (US-6512186-\$ or US-6217987-\$ or US-6418615-\$ or US-5704116-\$ or US-5953814-\$ or US-6713880-\$ or US-6714421-\$ or US-5578525-\$ or US-6806560-\$ or US-6249053-\$ or US-6064114-\$ or US-5598036-\$ or US-5467253-\$).did. or (JP-10173296-\$ or JP-11204683-\$). did.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25
L69	0	JP-1098045-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25
L70	1	JP-10098045-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25
L71	0	JP-10098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25
L72	0	1998jp10098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25
L73	0	1998jp1098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25
L74	1	"6249053".pn.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25

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L75	358	<i>mother with board with PCB</i>	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25
L76	237	<i>mother with board with PCB</i>	USPAT	OR	ON	2006/05/22 18:25
L77	49	<i>mother with board with interposer</i>	USPAT	OR	ON	2006/05/22 18:25
L78	75	<i>pcb with board with interposer</i>	USPAT	OR	ON	2006/05/22 18:25
L79	19	("20020041489" "4897918" "5222014" "5474458" "5477933" "5598036" "5783870" "5874776" "5973930" "5975409" "5990545" "6050832" "6059579" "6163462" "6174175" "6333563" "6335491" "6362437" "6479760").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L80	18	("3541222" "5477933" "5530288" "5759047" "5834848" "5973930" "6002168" "6050832" "6059579" "6088915" "6163462").PN. OR ("6335491").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L81	23	("3777221" "5375042" "5477933" "5535101").PN. OR ("5973930"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L82	6	<i>substrate with eutectic with paste with solder with contact</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L83	7	<i>board with eutectic with paste with solder with contact</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L84	7	<i>board with eutectic with paste with contact</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L85	29	<i>board with eutectic with paste with pad</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L86	2	"20040012930".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L87	10	("5578525" "5834848" "6249053" "6 285083" "6418615").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L88	281	<i>pad with wiring with short with circuit</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25

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L89	30	(US-20010013425-\$ or US-20010013653-\$ or US-20020066948-\$ or US-20020195272-\$ or US-20030201309-\$ or US-20040046252-\$ or US-20050199995-\$).did. or (US-5467253-\$ or US-5578525-\$ or US-5598036-\$ or US-5704116-\$ or US-5834848-\$ or US-5953814-\$ or US-6064114-\$ or US-6217987-\$ or US-6249053-\$ or US-6285083-\$ or US-6418615-\$ or US-6512186-\$ or US-6713880-\$ or US-6714421-\$ or US-6806560-\$ or US-6469370-\$ or US-6448783-\$ or US-6229249-\$ or US-6127729-\$ or US-5869356-\$ or US-5252844-\$).did. or (JP-10098045-\$ or JP-10173296-\$ or JP-11204683-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25
L90	1	"6854633".pn.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25
L91	30	("20030051770" "5128746" "5211763" "5385636" "5417771" "5482736" "5611476" "5851311" "5880017" "5904782" "5989362" "6053398" "6059173" "6059894" "6063647" "6100175" "6118179" "6168972" "6180504" "6184581" "6204080" "6234379" "6259036" "6260264" "6276599" "6283358" "6293456" "6297560" "6352881" "6402013").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L92	1	"6622380".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L93	30	("20030051770" "5128746" "5211763" "5385636" "5417771" "5482736" "5611476" "5851311" "5880017" "5904782" "5989362" "6053398" "6059173" "6059894" "6063647" "6100175" "6118179" "6168972" "6180504" "6184581" "6204080" "6234379" "6259036" "6260264" "6276599" "6283358" "6293456" "6297560" "6352881" "6402013").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L94	6	("5132879" "5160779" "5689091" "5756377" "5877553" "5901436").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L95	15	pad with wiring with shorting same substrate with (photoresistant mask solder near2 resist)	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25

EAST Search History

L96	18	pad with (trace wiring) with shorting same substrate with (photoresistant mask solder near2 resist)	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L97	18	pad with (trace wiring) with shorting same substrate with (photoresistant mask solder near2 resist)	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L98	0	("2003/0201309").URPN.	USPAT	OR	ON	2006/05/22 18:25
L99	52	("5,107,328" "5,128,831" "5,138,434" "5,593,927" "5,677,566" "5,696,033" "5,704,116" "5,729,896" "5,739,585" "5,801,350" "5,815,000" "5,842,273" "5,851,845" "5,866,953" "5,891,753" "5,893,726" "5,898,224" "5,933,713" "5,938,956" "5,946,553" "5,958,100" "5,985,043" "5,986,209" "5,989,941" "5,990,566" "5,994,784").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L100	50	("6,008,070" "6,008,014" "6,018,249" "6,020,629" "6,025,728" "6,028,365" "6,046,496" "6,048,744" "6,048,755" "6,049,125" "6,066,514" "6,072,233" "6,072,236" "6,075,288" "6,081,429" "6,089,920" "6,094,058" "6,097,087" "6,103,547" "6,107,122" "6,107,680" "6,117,382" "6,124,634" "6,150,717" "6,159,764").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L101	22	("6,326,687" "6,326,697" "6,326,698" "6,329,220" "6,329,222" "6,331,221" "6,331,453" "6,332,766" "6,451,709" "6,589,820" "6,664,139").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L102	52	("6,172,419" "6,184,465" "6,189,208" "6,198,172" "6,208,519" "6,210,992" "6,215,175" "6,228,548" "6,228,687" "6,229,202" "6,246,108" "6,252,308" "6,258,623" "6,258,624" "6,259,153" "6,277,671" "6,284,571" "6,291,894" "6,294,839" "6,303,981" "6,303,985" "6,310,390" "6,314,639" "6,316,285" "6,326,242" "6,326,244").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L103	10	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) same (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) and (solder near2 mask solder near2 resist resist near2 pattern) same(solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25

EAST Search History

L104	695	pad with (prevent\$4 avoid) with oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L105	1092	insulat\$5 with pad with solder with (ball bump c4 flip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L106	388	L105 and pad with (protect\$5 prevent avoid)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L107	2083	protect\$4 with exposed with pad	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L108	1950	protect\$4 with exposed with pad and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L109	0	US005578525A	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L110	0	solde adj mask with flux and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L111	0	solder near2 mask with flux and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L112	0	solder near2 mask and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25

EAST Search History

L113	8221	solder near2 mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L114	0	L113 and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L115	627	solder near2 mask same PCB	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L116	369	L115 and (IC chip integrated adj circuit wafer die semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L117	537	solder near2 mask same BGA	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L118	377	L117 and (IC chip integrated adj circuit wafer die semiconductor).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:25
L119	0	JP-1098045-\$.did.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25
L120	0	JP-10098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25
L121	0	1998jp10098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25
L122	0	1998jp1098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25
L123	358	mother with board with PCB	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:25
L124	7	board with eutectic with paste with contact	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25

EAST Search History

L125	1	"6217987".pn.	USPAT	OR	ON	2006/05/22 18:25
L126	1	"5,178,685".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:25
L127	1	"6622380".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/05/22 18:25
L128	1	JP-10098045-\$.did.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:26
L129	1	"6249053".pn.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:26
L130	14	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) with (solder near2 mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L131	77	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) and (solder near2 mask solder near2 resist resist near2 pattern) and(solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L132	60	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with pad with (mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L133	80	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with pad and pad with (prevent\$4 avoid) with oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L134	3	("4489365" "5237131" "6011695").PN. OR ("6714421").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26

EAST Search History

L135	86	("5107328" "5128831" "5138434" "5593927" "5677566" "5696033" "5704116" "5729896" "5739585" "5801350" "5815000" "5842273" "5851845" "5866953" "5891753" "5893726" "5898224" "5933713" "5938956" "5946553" "5958100" "5985043" "5986209" "5989941" "5990566" "5994784" "6008070" "6018249" "6020629" "6025728" "6028365" "6046496" "6048744" "6048755" "6049125" "6066514" "6072233" "6075288" "6081429" "6089920" "6094058" "6097087" "6103547" "6107122" "6107680" "6117382" "6124634" "6150717" "6159764" "6172419" "6184465" "6189208" "6198172" "6208519" "6210992" "6215175" "6228548" "6228687" "6229202" "6246108" "6258623" "6258624" "6259153" "6277671" "6284571" "6291894" "6294839" "6303981" "6303985" "6310390" "6314639" "6316285" "6326242" "6326244" "6326687" "6326697" "6326698" "6329220" "6329222" "6331221" "6331453" "6332766" "RE36469").PN. OR ("6622380").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L136	44	("2672681" "3235414" "3264146" "3970239" "4216035" "4601763" "4940181" "5004508" "5122200" "5177134" "5255839" "5386624" "5435481" "5442240" "5499756" "5583747").PN. OR ("5704116"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L137	38	("4604644" "5084961" "5089440" "5121190" "5194930" "5274913" "5400950" "5542601" "5578525" "5615477" "5704116" "5710071").PN. OR ("5953814"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L138	144	andujar.xa.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L139	70	L138 and pad	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L140	4	("5391924" "6011694" "6054652").PN. OR ("6791199"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L141	61	("4791075" "5216278" "5474957" "5602059" "5650662" "5663530" "5679978" "5710695" "5737191").PN. OR ("6011694"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26

EAST Search History

L142	66	protect\$4 with exposed with pad and "174"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L143	2	"6217987".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L144	46	("3356624" "4504607" "4510276" "4615950" "4713298" "4750976" "4752499" "4820549" "4888269" "4902726" "4948700" "4990395" "5009982" "5021472" "5055321" "5055378" "5061744" "5137936" "5175060" "5302492" "5519177" "5532094" "5741575" "5753722" "5948514").PN. OR ("6217987"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L145	16	("5321210" "5322593" "5337466" "5426849" "5590461" "5628852" "5686702" "5745984" "6049123" "6214641").PN. OR ("6418615"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L146	2	"6418615".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L147	2	"5578525".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L148	86	"5,432,734"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L149	2	"5,432,734".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L150	28	("5578525").URPN.	USPAT	OR	ON	2006/05/22 18:26

EAST Search History

L151	32	("20010013653" "20020012234" "4801998" "5194934" "5222014" "5231036" "5463229" "5578525" "5579207" "5786589" "5821532" "5858815" "5867368" "5907151" "5925898" "5949655" "5962810" "5973337" "5977624" "6005965" "6011310" "6028354" "6046070" "6122009" "6130448" "6143981" "6144507" "6247229" "6281568" "6291884" "6342406" "6396043"). PN. OR ("6627864").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L152	12	("5178685").URPN.	USPAT	OR	ON	2006/05/22 18:26
L153	24	("3823469" "4050621" "4604644" "4605153" "4803450" "4837609" "5060844" "5133495" "5148265" "5148266" "5160409" "5400220" "5519580" "5534127" "5547740" "5551627" "5558271" "5615477" "5801446" "5808874" "5849750" "5885849" "6130448").PN. OR ("6465747").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L154	104	trace with pad with short with circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/05/22 18:26
L155	58	pad with circuit adj board with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L156	2	"6806560".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L157	15	("4786545" "5055321" "5278429" "5473512" "5519251" "5756380" "5816478" "5834832" "5872399" "5925403" "6197615" "6286207" "6288451" "6323542" "6344753").PN. OR ("6806560"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26

EAST Search History

L158	18	(US-20010013425-\$ or US-20020195272-\$ or US-20030201309-\$ or US-20010013653-\$ or US-20040046252-\$ or US-20020066948-\$).did. or (US-6512186-\$ or US-6217987-\$ or US-6418615-\$ or US-5704116-\$ or US-5953814-\$ or US-6713880-\$ or US-6714421-\$ or US-5578525-\$ or US-6806560-\$ or US-6249053-\$ or US-6064114-\$ or US-5598036-\$ or US-5467253-\$).did. or (JP-10173296-\$ or JP-11204683-\$). did.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:26
L159	49	<i>mother with board with interposer</i>	USPAT	OR	ON	2006/05/22 18:26
L160	75	<i>pcb with board with interposer</i>	USPAT	OR	ON	2006/05/22 18:26
L161	19	("20020041489" "4897918" "5222014" "5474458" "5477933" "5598036" "5783870" "5874776" "5973930" "5975409" "5990545" "6050832" "6059579" "6163462" "6174175" "6333563" "6335491" "6362437" "6479760").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L162	18	("3541222" "5477933" "5530288" "5759047" "5834848" "5973930" "6002168" "6050832" "6059579" "6088915" "6163462").PN. OR ("6335491").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L163	23	("3777221" "5375042" "5477933" "5535101").PN. OR ("5973930"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L164	6	<i>substrate with eutectic with paste with solder with contact</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L165	7	<i>board with eutectic with paste with solder with contact</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L166	29	<i>board with eutectic with paste with pad</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L167	176	L99 L100 L101 L102	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26

EAST Search History

L168	223	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) and (solder near2 mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L169	144	andujar.xa.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L170	129	(hole opening) with (solder near2 (resist mask) with trace)	USPAT	OR	ON	2006/05/22 18:26
L171	195	L115 and (IC chip integrated adj circuit wafer die semiconductor).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L172	237	mother with board with PCB	USPAT	OR	ON	2006/05/22 18:26
L173	371	L106 and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L174	328	L118 not L171	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L175	377	L117 and (IC chip integrated adj circuit wafer die semiconductor).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L176	464	protect\$4 with exposed with pad with (insulat\$3 dielectric) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L177	15	andujar.xp.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26

EAST Search History

L178	52	("5,107,328" "5,128,831" "5,138,434" "5,593,927" "5,677,566" "5,696,033" "5,704,116" "5,729,896" "5,739,585" "5,801,350" "5,815,000" "5,842,273" "5,851,845" "5,866,953" "5,891,753" "5,893,726" "5,898,224" "5,933,713" "5,938,956" "5,946,553" "5,958,100" "5,985,043" "5,986,209" "5,989,941" "5,990,566" "5,994,784").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L179	50	("6,008,070" "6,008,014" "6,018,249" "6,020,629" "6,025,728" "6,028,365" "6,046,496" "6,048,744" "6,048,755" "6,049,125" "6,066,514" "6,072,233" "6,072,236" "6,075,288" "6,081,429" "6,089,920" "6,094,058" "6,097,087" "6,103,547" "6,107,122" "6,107,680" "6,117,382" "6,124,634" "6,150,717" "6,159,764").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L180	22	("6,326,687" "6,326,697" "6,326,698" "6,329,220" "6,329,222" "6,331,221" "6,331,453" "6,332,766" "6,451,709" "6,589,820" "6,664,139").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L181	52	("6,172,419" "6,184,465" "6,189,208" "6,198,172" "6,208,519" "6,210,992" "6,215,175" "6,228,548" "6,228,687" "6,229,202" "6,246,108" "6,252,308" "6,258,623" "6,258,624" "6,259,153" "6,277,671" "6,284,571" "6,291,894" "6,294,839" "6,303,981" "6,303,985" "6,310,390" "6,314,639" "6,316,285" "6,326,242" "6,326,244").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L182	10	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) same (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) and (solder near2 mask solder near2 resist resist near2 pattern) same(solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L183	695	pad with (prevent\$4 avoid) with oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26

EAST Search History

L184	1092	insulat\$5 with pad with solder with (ball bump c4 flip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L185	388	L184 and pad with (protect\$5 prevent avoid)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L186	2083	protect\$4 with exposed with pad	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L187	1950	protect\$4 with exposed with pad and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L188	0	US005578525A	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L189	0	solde adj mask with flux and "174". ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L190	0	solder near2 mask with flux and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L191	0	solder near2 mask and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L192	8221	solder near2 mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26

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L193	0	L192 and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L194	627	solder near2 mask same PCB	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L195	369	L194 and (IC chip integrated adj circuit wafer die semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L196	537	solder near2 mask same BGA	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L197	377	L196 and (IC chip integrated adj circuit wafer die semiconductor).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L198	0	JP-1098045-\$.did.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:26
L199	0	JP-10098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:26
L200	0	1998jp10098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:26
L201	0	1998jp1098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:26
L202	358	mother with board with PCB	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:26
L203	7	board with eutectic with paste with contact	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L204	15	pad with wiring with shorting same substrate with (photoresistant mask solder near2 resist)	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:26
L205	0	("2003/0201309").URPN.	USPAT	OR	ON	2006/05/22 18:26

EAST Search History

L206	52	("5,107,328" "5,128,831" "5,138,434" "5,593,927" "5,677,566" "5,696,033" "5,704,116" "5,729,896" "5,739,585" "5,801,350" "5,815,000" "5,842,273" "5,851,845" "5,866,953" "5,891,753" "5,893,726" "5,898,224" "5,933,713" "5,938,956" "5,946,553" "5,958,100" "5,985,043" "5,986,209" "5,989,941" "5,990,566" "5,994,784").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L207	50	("6,008,070" "6,008,014" "6,018,249" "6,020,629" "6,025,728" "6,028,365" "6,046,496" "6,048,744" "6,048,755" "6,049,125" "6,066,514" "6,072,233" "6,072,236" "6,075,288" "6,081,429" "6,089,920" "6,094,058" "6,097,087" "6,103,547" "6,107,122" "6,107,680" "6,117,382" "6,124,634" "6,150,717" "6,159,764").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L208	22	("6,326,687" "6,326,697" "6,326,698" "6,329,220" "6,329,222" "6,331,221" "6,331,453" "6,332,766" "6,451,709" "6,589,820" "6,664,139").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L209	52	("6,172,419" "6,184,465" "6,189,208" "6,198,172" "6,208,519" "6,210,992" "6,215,175" "6,228,548" "6,228,687" "6,229,202" "6,246,108" "6,252,308" "6,258,623" "6,258,624" "6,259,153" "6,277,671" "6,284,571" "6,291,894" "6,294,839" "6,303,981" "6,303,985" "6,310,390" "6,314,639" "6,316,285" "6,326,242" "6,326,244").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L210	10	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) same (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) and (solder near2 mask solder near2 resist resist near2 pattern) same(solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26
L211	695	pad with (prevent\$4 avoid) with oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:26

EAST Search History

L212	1092	insulat\$5 with pad with solder with (ball bump c4 flip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L213	388	L212 and pad with (protect\$5 prevent avoid)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L214	2083	protect\$4 with exposed with pad	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L215	1950	protect\$4 with exposed with pad and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L216	0	US005578525A	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L217	0	solde adj mask with flux and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L218	0	solder near2 mask with flux and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L219	0	solder near2 mask and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L220	8221	solder near2 mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27

EAST Search History

L221	0	L220 and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L222	627	solder near2 mask same PCB	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L223	369	L222 and (IC chip integrated adj circuit wafer die semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L224	537	solder near2 mask same BGA	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L225	377	L224 and (IC chip integrated adj circuit wafer die semiconductor).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L226	0	JP-1098045-\$.did.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:27
L227	0	JP-10098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:27
L228	0	1998jp10098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:27
L229	0	1998jp1098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:27
L230	358	mother with board with PCB	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:27
L231	7	board with eutectic with paste with contact	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L232	144	andujar.xa.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L233	1	"6217987".pn.	USPAT	OR	ON	2006/05/22 18:27

EAST Search History

L234	1	"5,178,685".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L235	1	"6622380".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/05/22 18:27
L236	1	JP-10098045-\$.did.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:27
L237	1	"6249053".pn.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:27
L238	1	"6854633".pn.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:27
L239	1	"6622380".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L240	1	"6217987".pn.	USPAT	OR	ON	2006/05/22 18:27
L241	1	"5,178,685".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L242	1	"6622380".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/05/22 18:27
L243	1	JP-10098045-\$.did.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:27
L244	1	"6249053".pn.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:27
L245	14	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) with (solder near2 mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L246	77	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) and (solder near2 mask solder near2 resist resist near2 pattern) and(solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27

EAST Search History

L247	60	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with pad with (mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L248	80	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with pad and pad with (prevent\$4 avoid) with oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L249	3	("4489365" "5237131" "6011695").PN. OR ("6714421").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L250	86	("5107328" "5128831" "5138434" "5593927" "5677566" "5696033" "5704116" "5729896" "5739585" "5801350" "5815000" "5842273" "5851845" "5866953" "5891753" "5893726" "5898224" "5933713" "5938956" "5946553" "5958100" "5985043" "5986209" "5989941" "5990566" "5994784" "6008070" "6018249" "6020629" "6025728" "6028365" "6046496" "6048744" "6048755" "6049125" "6066514" "6072233" "6075288" "6081429" "6089920" "6094058" "6097087" "6103547" "6107122" "6107680" "6117382" "6124634" "6150717" "6159764" "6172419" "6184465" "6189208" "6198172" "6208519" "6210992" "6215175" "6228548" "6228687" "6229202" "6246108" "6258623" "6258624" "6259153" "6277671" "6284571" "6291894" "6294839" "6303981" "6303985" "6310390" "6314639" "6316285" "6326242" "6326244" "6326687" "6326697" "6326698" "6329220" "6329222" "6331221" "6331453" "6332766" "RE36469").PN. OR ("6622380").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L251	44	("2672681" "3235414" "3264146" "3970239" "4216035" "4601763" "4940181" "5004508" "5122200" "5177134" "5255839" "5386624" "5435481" "5442240" "5499756" "5583747").PN. OR ("5704116").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27

EAST Search History

L252	38	("4604644" "5084961" "5089440" "5121190" "5194930" "5274913" "5400950" "5542601" "5578525" "5615477" "5704116" "5710071").PN. OR ("5953814"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L253	144	andujar.xa.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L254	70	L253 and pad	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L255	4	("5391924" "6011694" "6054652").PN. OR ("6791199"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L256	61	("4791075" "5216278" "5474957" "5602059" "5650662" "5663530" "5679978" "5710695" "5737191").PN. OR ("6011694"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L257	66	protect\$4 with exposed with pad and "174"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L258	2	"6217987".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L259	46	("3356624" "4504607" "4510276" "4615950" "4713298" "4750976" "4752499" "4820549" "4888269" "4902726" "4948700" "4990395" "5009982" "5021472" "5055321" "5055378" "5061744" "5137936" "5175060" "5302492" "5519177" "5532094" "5741575" "5753722" "5948514").PN. OR ("6217987"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L260	16	("5321210" "5322593" "5337466" "5426849" "5590461" "5628852" "5686702" "5745984" "6049123" "6214641").PN. OR ("6418615"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L261	2	"6418615".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27

EAST Search History

L262	2	"5578525".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L263	86	"5,432,734"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L264	2	"5,432,734".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L265	28	("5578525").URPN.	USPAT	OR	ON	2006/05/22 18:27
L266	32	("20010013653" "20020012234" "4801998" "5194934" "5222014" "5231036" "5463229" "5578525" "5579207" "5786589" "5821532" "5858815" "5867368" "5907151" "5925898" "5949655" "5962810" "5973337" "5977624" "6005965" "6011310" "6028354" "6046070" "6122009" "6130448" "6143981" "6144507" "6247229" "6281568" "6291884" "6342406" "6396043"). PN. OR ("6627864").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L267	12	("5178685").URPN.	USPAT	OR	ON	2006/05/22 18:27
L268	24	("3823469" "4050621" "4604644" "4605153" "4803450" "4837609" "5060844" "5133495" "5148265" "5148266" "5160409" "5400220" "5519580" "5534127" "5547740" "5551627" "5558271" "5615477" "5801446" "5808874" "5849750" "5885849" "6130448").PN. OR ("6465747").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L269	58	pad with circuit adj board with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27
L270	2	"6806560".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:27

EAST Search History

L271	15	("4786545" "5055321" "5278429" "5473512" "5519251" "5756380" "5816478" "5834832" "5872399" "5925403" "6197615" "6286207" "6288451" "6323542" "6344753").PN. OR ("6806560").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L272	18	(US-20010013425-\$ or US-20020195272-\$ or US-20030201309-\$ or US-20010013653-\$ or US-20040046252-\$ or US-20020066948-\$).did. or (US-6512186-\$ or US-6217987-\$ or US-6418615-\$ or US-5704116-\$ or US-5953814-\$ or US-6713880-\$ or US-6714421-\$ or US-5578525-\$ or US-6806560-\$ or US-6249053-\$ or US-6064114-\$ or US-5598036-\$ or US-5467253-\$).did. or (JP-10173296-\$ or JP-11204683-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:27
L273	49	<i>mother with board with interposer</i>	USPAT	OR	ON	2006/05/22 18:27
L274	75	<i>pcb with board with interposer</i>	USPAT	OR	ON	2006/05/22 18:27
L275	19	("20020041489" "4897918" "5222014" "5474458" "5477933" "5598036" "5783870" "5874776" "5973930" "5975409" "5990545" "6050832" "6059579" "6163462" "6174175" "6333563" "6335491" "6362437" "6479760").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L276	18	("3541222" "5477933" "5530288" "5759047" "5834848" "5973930" "6002168" "6050832" "6059579" "6088915" "6163462").PN. OR ("6335491").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L277	23	("3777221" "5375042" "5477933" "5535101").PN. OR ("5973930").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:27
L278	6	<i>substrate with eutectic with paste with solder with contact</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L279	7	<i>board with eutectic with paste with solder with contact</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L280	29	<i>board with eutectic with paste with pad</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L281	2	"20040012930".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28

EAST Search History

L282	10	("5578525" "5834848" "6249053" "6285083" "6418615").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L283	30	(US-20010013425-\$ or US-20010013653-\$ or US-20020066948-\$ or US-20020195272-\$ or US-20030201309-\$ or US-20040046252-\$ or US-20050199995-\$).did. or (US-5467253-\$ or US-5578525-\$ or US-5598036-\$ or US-5704116-\$ or US-5834848-\$ or US-5953814-\$ or US-6064114-\$ or US-6217987-\$ or US-6249053-\$ or US-6285083-\$ or US-6418615-\$ or US-6512186-\$ or US-6713880-\$ or US-6714421-\$ or US-6806560-\$ or US-6469370-\$ or US-6448783-\$ or US-6229249-\$ or US-6127729-\$ or US-5869356-\$ or US-5252844-\$).did. or (JP-10098045-\$ or JP-10173296-\$ or JP-11204683-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:28
L284	30	("20030051770" "5128746" "5211763" "5385636" "5417771" "5482736" "5611476" "5851311" "5880017" "5904782" "5989362" "6053398" "6059173" "6059894" "6063647" "6100175" "6118179" "6168972" "6180504" "6184581" "6204080" "6234379" "6259036" "6260264" "6276599" "6283358" "6293456" "6297560" "6352881" "6402013").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L285	30	("20030051770" "5128746" "5211763" "5385636" "5417771" "5482736" "5611476" "5851311" "5880017" "5904782" "5989362" "6053398" "6059173" "6059894" "6063647" "6100175" "6118179" "6168972" "6180504" "6184581" "6204080" "6234379" "6259036" "6260264" "6276599" "6283358" "6293456" "6297560" "6352881" "6402013").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L286	6	("5132879" "5160779" "5689091" "5756377" "5877553" "5901436").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L287	18	pad with (trace wiring) with shorting same substrate with (photoresistant mask solder near2 resist)	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28

EAST Search History

L288	18	pad with (trace wiring) with shorting same substrate with (photoresistant mask solder near2 resist)	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L289	14	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) with (solder near2 mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L290	77	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) and (solder near2 mask solder near2 resist resist near2 pattern) and(solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L291	60	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with pad with (mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L292	80	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with pad and pad with (prevent\$4 avoid) with oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L293	3	("4489365" "5237131" "6011695").PN. OR ("6714421").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28

EAST Search History

L294	86	("5107328" "5128831" "5138434" "5593927" "5677566" "5696033" "5704116" "5729896" "5739585" "5801350" "5815000" "5842273" "5851845" "5866953" "5891753" "5893726" "5898224" "5933713" "5938956" "5946553" "5958100" "5985043" "5986209" "5989941" "5990566" "5994784" "6008070" "6018249" "6020629" "6025728" "6028365" "6046496" "6048744" "6048755" "6049125" "6066514" "6072233" "6075288" "6081429" "6089920" "6094058" "6097087" "6103547" "6107122" "6107680" "6117382" "6124634" "6150717" "6159764" "6172419" "6184465" "6189208" "6198172" "6208519" "6210992" "6215175" "6228548" "6228687" "6229202" "6246108" "6258623" "6258624" "6259153" "6277671" "6284571" "6291894" "6294839" "6303981" "6303985" "6310390" "6314639" "6316285" "6326242" "6326244" "6326687" "6326697" "6326698" "6329220" "6329222" "6331221" "6331453" "6332766" "RE36469").PN. OR ("6622380").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L295	44	("2672681" "3235414" "3264146" "3970239" "4216035" "4601763" "4940181" "5004508" "5122200" "5177134" "5255839" "5386624" "5435481" "5442240" "5499756" "5583747").PN. OR ("5704116"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L296	38	("4604644" "5084961" "5089440" "5121190" "5194930" "5274913" "5400950" "5542601" "5578525" "5615477" "5704116" "5710071").PN. OR ("5953814"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L297	70	L232 and pad	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L298	4	("5391924" "6011694" "6054652").PN. OR ("6791199"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L299	61	("4791075" "5216278" "5474957" "5602059" "5650662" "5663530" "5679978" "5710695" "5737191").PN. OR ("6011694"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28

EAST Search History

L300	66	protect\$4 with exposed with pad and "174"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L301	2	"6217987".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L302	46	("3356624" "4504607" "4510276" "4615950" "4713298" "4750976" "4752499" "4820549" "4888269" "4902726" "4948700" "4990395" "5009982" "5021472" "5055321" "5055378" "5061744" "5137936" "5175060" "5302492" "5519177" "5532094" "5741575" "5753722" "5948514").PN. OR ("6217987"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L303	16	("5321210" "5322593" "5337466" "5426849" "5590461" "5628852" "5686702" "5745984" "6049123" "6214641").PN. OR ("6418615"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L304	2	"6418615".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L305	2	"5578525".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L306	86	"5,432,734"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L307	2	"5,432,734".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L308	28	("5578525").URPN.	USPAT	OR	ON	2006/05/22 18:28

EAST Search History

L309	32	("20010013653" "20020012234" "4801998" "5194934" "5222014" "5231036" "5463229" "5578525" "5579207" "5786589" "5821532" "5858815" "5867368" "5907151" "5925898" "5949655" "5962810" "5973337" "5977624" "6005965" "6011310" "6028354" "6046070" "6122009" "6130448" "6143981" "6144507" "6247229" "6281568" "6291884" "6342406" "6396043"). PN. OR ("6627864").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L310	12	("5178685").URPN.	USPAT	OR	ON	2006/05/22 18:28
L311	24	("3823469" "4050621" "4604644" "4605153" "4803450" "4837609" "5060844" "5133495" "5148265" "5148266" "5160409" "5400220" "5519580" "5534127" "5547740" "5551627" "5558271" "5615477" "5801446" "5808874" "5849750" "5885849" "6130448").PN. OR ("6465747").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L312	58	pad with circuit adj board with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L313	2	"6806560".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L314	15	("4786545" "5055321" "5278429" "5473512" "5519251" "5756380" "5816478" "5834832" "5872399" "5925403" "6197615" "6286207" "6288451" "6323542" "6344753").PN. OR ("6806560"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L315	18	(US-20010013425-\$ or US-20020195272-\$ or US-20030201309-\$ or US-20010013653-\$ or US-20040046252-\$ or US-20020066948-\$).did. or (US-6512186-\$ or US-6217987-\$ or US-6418615-\$ or US-5704116-\$ or US-5953814-\$ or US-6713880-\$ or US-6714421-\$ or US-5578525-\$ or US-6806560-\$ or US-6249053-\$ or US-6064114-\$ or US-5598036-\$ or US-5467253-\$).did. or (JP-10173296-\$ or JP-11204683-\$). did.	US-PGPUB; USPAT; JPO	OR	ON	2006/05/22 18:28

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L316	49	<i>mother with board with interposer</i>	USPAT	OR	ON	2006/05/22 18:28
L317	75	<i>pcb with board with interposer</i>	USPAT	OR	ON	2006/05/22 18:28
L318	19	<i>("20020041489" "4897918" "5222014" "5474458" "5477933" "5598036" "5783870" "5874776" "5973930" "5975409" "5990545" "6050832" "6059579" "6163462" "6174175" "6333563" "6335491" "6362437" "6479760").PN.</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L319	18	<i>("3541222" "5477933" "5530288" "5759047" "5834848" "5973930" "6002168" "6050832" "6059579" "6088915" "6163462").PN. OR ("6335491").URPN.</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L320	23	<i>("3777221" "5375042" "5477933" "5535101").PN. OR ("5973930").URPN.</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L321	6	<i>substrate with eutectic with paste with solder with contact</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L322	7	<i>board with eutectic with paste with solder with contact</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L323	29	<i>board with eutectic with paste with pad</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L324	15	<i>andujar.xp.</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L325	176	<i>L178 L179 L180 L181</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L326	144	<i>andujar.xa.</i>	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L327	129	<i>(hole opening) with (solder near2 (resist mask) with trace)</i>	USPAT	OR	ON	2006/05/22 18:28
L328	104	<i>trace with pad with short with circuit</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/05/22 18:28

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L329	195	L194 and (IC chip integrated adj circuit wafer die semiconductor).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L330	104	trace with pad with short with circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/05/22 18:28
L331	176	L206 L207 L208 L209	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L332	144	andujar.xa.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/22 18:28
L333	129	(hole opening) with (solder near2 (resist mask) with trace)	USPAT	OR	ON	2006/05/22 18:28
L334	195	L222 and (IC chip integrated adj circuit wafer die semiconductor).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L335	223	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) and (solder near2 mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:28
L336	237	mother with board with PCB	USPAT	OR	ON	2006/05/22 18:28
L337	281	pad with wiring with short with circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:29
L338	223	(PCB insulat\$4 near2 substrate dielectr\$4 near2 substrate) with (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) and (solder near2 mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:29

EAST Search History

L339	237	<i>mother with board with PCB</i>	USPAT	OR	ON	2006/05/22 18:29
L340	371	<i>L185 and (integrated near2 circuit IC chip die wafer semiconductor)</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:29
L341	328	<i>L197 not L329</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:29
L342	377	<i>L196 and (IC chip integrated adj circuit wafer die semiconductor).ab.</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:29
L343	371	<i>L213 and (integrated near2 circuit IC chip die wafer semiconductor)</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:29
L344	328	<i>L225 not L334</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:29
L345	377	<i>L224 and (IC chip integrated adj circuit wafer die semiconductor).ab.</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:29
L346	464	<i>protect\$4 with exposed with pad with (insulat\$3 dielectric) and (integrated near2 circuit IC chip die wafer semiconductor)</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:29
L347	464	<i>protect\$4 with exposed with pad with (insulat\$3 dielectric) and (integrated near2 circuit IC chip die wafer semiconductor)</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/22 18:29